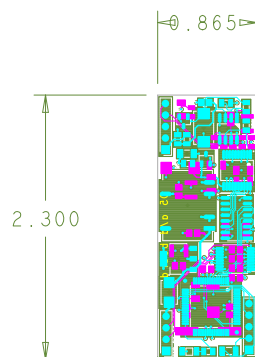


* SURFACE - AIR 0 MIL
L1: TOP CONDUCTOR - COPPER 1.4 MIL
* DIELECTRIC - FR-4 5.1 MIL
* DIELECTRIC - FR-4 4.7 MIL
L2: IN1 CONDUCTOR - COPPER 1.4 MIL

* DIELECTRIC - FR-4 35 MIL

L3: IN2 CONDUCTOR - COPPER 1.4 MIL
* DIELECTRIC - FR-4 4.7 MIL
* DIELECTRIC - FR-4 5.1 MIL
L4: BOTTOM CONDUCTOR - COPPER 1.4 MIL
* SURFACE - AIR 0 MIL

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 60.2 MIL



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
Ø	10.0	PLATED	88
⌀	44.0	PLATED	14

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

- BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
- THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
- MATERIAL:
 - a. FR4 PER IPC 4101B/24 /26 /28
 - b. SIGNAL LAYERS TO BE 1 OZ. COPPER;
 - c. PLANE LAYERS TO BE 1 OZ. COPPER;
 - d. OVERALL THICKNESS TO BE 0.062" +/- 10%
- LEGEND:
 - a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
- SOLDERMASK:
 - a. APPLY TQUD PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR GREEN, BOTH SIDES.
- PLATING FINISH:
 - a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
 - ~~b. IMMERSION SILVER PLATING.~~
- PROCESS ALLOWANCES:
 - a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH
 - b. HOLE DIMENSIONS APPLY AFTER PLATING.
 - c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
 - d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
 - e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
 - f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
 - g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	05 A/D BOARD		
			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE		
			7700 SANDHOLDT ROAD		
			MOSS LANDING, CA		
	DESIGNED BY: CRAIG OKUDA		SIZE B	REVISION -	DWG NO 0000
LAYOUT BY: JOSE ROSAL			SCALE 1-1		SHEET 1-1